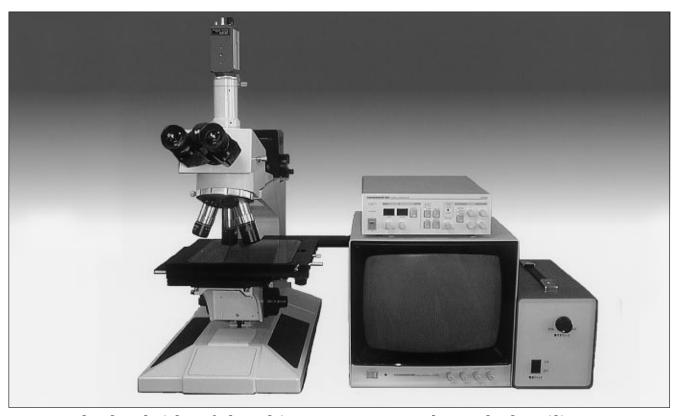


TENTATIVE DATA SHEET

INFRARED IC INTERNAL INSPECTION SYSTEM C2955



From the backside of the chip, you can see through the silicon substrate to the patterns of the chip by means of an infrared light. A newly developed infrared CCD camera is used to inspect pattern images more clearly and easily than ever before.

The C2955 is an IC internal inspection system incorporating an infrared microscope and an infrared CCD camera. Use of a newly developed infrared CCD camera enables a high sensitivity approximately ten times that of conventional systems (in comparisons by HAMAMATSU), at a wavelength of 1.0 µm, making it possible to obtain sharp, clear images with high resolution. Using an infrared light which is transmitted through the silicon substrate enables observation of the interconnect lines in the IC, the wire bonding status, and the die bonding conditions, along with the diffusion zone conditions, without damaging the part under observation. Observation can be done from the back side, when the sample is prepared by scraping away the molding on the side opposite the surface of the silicon substrate. Because the metal wiring is never touched in the inspection process, precise testing can be carried out under optimum conditions, making it possible to inspect the condition of the diffusion zones, the multilayer interconnect lines, the Al-Si nodules wire bonding interfaces, and die bonding details.

- Best suited for flip-chip evaluation
- No damage to part under observation
- High sensitivity, high resolution
- Built-in contrast enhancement function
- Shading correction function

SPECIFICATIONS

Infrared CCD Camera (camera head, camera control unit)

Power consumption 20 VA

Video Monitor

CRT......12-inch/Black and white, high-resolution model

Resolution (horizontal center) 900 TV lines min.

Power consumption 38 VA

Infrared Microscope

Revolver5 holes

Environmental Conditions

Ambient operating temperature range 0 to +40°C Ambient storage temperature range -10 to +50°C

Ambient operating/storage humidity 90% max. (with no condensation)

COMPONENTS

- Infrared CCD camera
- · Camera control unit
- Video monitor
- Infrared microscope (including light source dimmer transformer*)
- Cables: 1 set
- * Specify the line voltage at ordering.

APPLICATIONS

- Inspection of flip-chip and other packaged IC devices
- Testing for abnormalities (defects, failures) in metal and polysilicon wiring
- Observation of wire bonding
- Observation of various types of die bonding zones

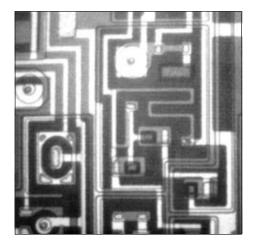
or omissions. Specifications and external appearance are subject to change without notice.

- Simultaneous inspection of Al-Si nodules and multiple patterns
- Observation of pattern diffusion into substrate
- Identification of ESD failure locations

OPTIONS

• C7103 IC Backside Polishing System

IMAGE EXAMPLE



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